

## N-CHANNEL SILICON POWER MOS-FET

## F-III SERIES

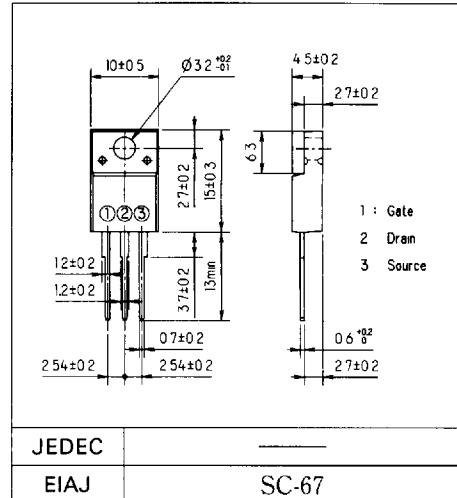
### ■ Features

- High current
- Low on-resistance
- No secondary breakdown
- Low driving power
- High forward Transconductance

### ■ Applications

- Motor controllers
- General purpose power amplifier
- DC-DC converters

### ■ Outline Drawings



### ■ Max. Ratings and Characteristics

#### ● Absolute Maximum Ratings( $T_c = 25^\circ\text{C}$ )

Items	Symbols	Ratings	Units
Drain-source voltage	$V_{DSS}$	60	V
Continuous drain current	$I_D$	13	A
Pulsed drain current	$I_{D(\text{puls})}$	52	A
Continuous reverse drain current	$I_{DR}$	13	A
Gate-source peak voltage	$V_{GSS}$	$\pm 20$	V
Max. power dissipation	$P_D$	30	W
Operating and storage temperature range	$T_{ch}$	150	$^\circ\text{C}$
	$T_{stg}$	-55 ~ +150	$^\circ\text{C}$

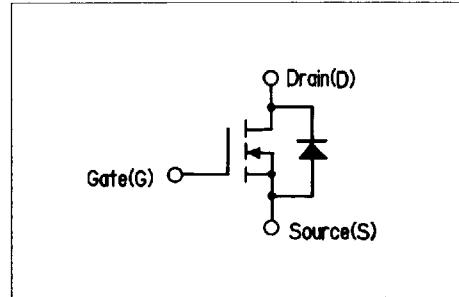
#### ● Electrical Characteristics( $T_c = 25^\circ\text{C}$ )

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1\text{mA}$ $V_{GS} = 0\text{V}$	60			V
Gate threshold voltage	$V_{GS(\text{th})}$	$I_D = 1\text{mA}$ $V_{DS} = V_{GS}$	1.0	1.5	2.5	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 60\text{V}$ $T_{ch} = 25^\circ\text{C}$ $V_{GS} = 0\text{V}$ $T_{ch} = 125^\circ\text{C}$	10	500	500	$\mu\text{A}$
Gate-source leakage current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$ $V_{DS} = 0\text{V}$	10	100	100	nA
Drain-source on-state resistance	$R_{DS(\text{on})}$	$I_D = 7.0\text{A}$ $V_{GS} = 4\text{V}$	0.12	0.19	0.19	$\Omega$
		$I_D = 7.0\text{A}$ $V_{GS} = 10\text{V}$	0.08	0.12	0.12	$\Omega$
Forward transconductance	$g_{fs}$	$I_D = 7.0\text{A}$ $V_{DS} = 25\text{V}$	5	11		S
Input capacitance	$C_{iss}$	$V_{DS} = 25\text{V}$	500	750		pF
Output capacitance	$C_{oss}$	$V_{GS} = 0\text{V}$	200	300		
Reverse transfer capacitance	$C_{rss}$	$f = 1\text{MHz}$	60	90		
Turn-on time $t_{on}$ ( $t_{on} + t_{d(on)} + t_r$ )	$t_{d(on)}$ $t_r$	$V_{CC} = 30\text{V}$ $I_D = 13\text{A}$	10	15		ns
Turn-off time $t_{off}$ ( $t_{d(off)} + t_f$ )	$t_{d(off)}$ $t_f$	$V_{GS} = 10\text{V}$ $R_G = 25\Omega$	30	45		
Diode forward on-voltage	$V_{SD}$	$I_F = 2 \times I_{DR}$ $V_{GS} = 0\text{V}$ $T_{ch} = 25^\circ\text{C}$	1.16	1.74	1.74	V
Reverse recovery time	$t_{rr}$	$I_F = I_{DR}$ $di/dt = 100\text{A}/\mu\text{s}$ $T_{ch} = 25^\circ\text{C}$	50			ns

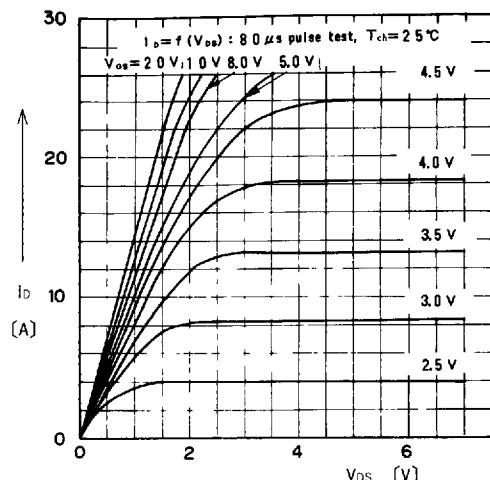
#### ● Thermal Characteristics

Items	Symbols	Test Conditions	Min.	Typ.	Max.	Units
Thermal Resistance	$R_{th(ch-a)}$	channel to air			62.5	$^\circ\text{C/W}$
	$R_{th(ch-c)}$	channel to case			4.17	$^\circ\text{C/W}$

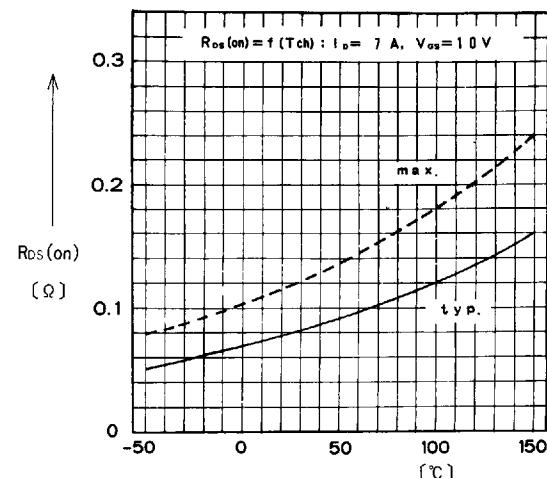
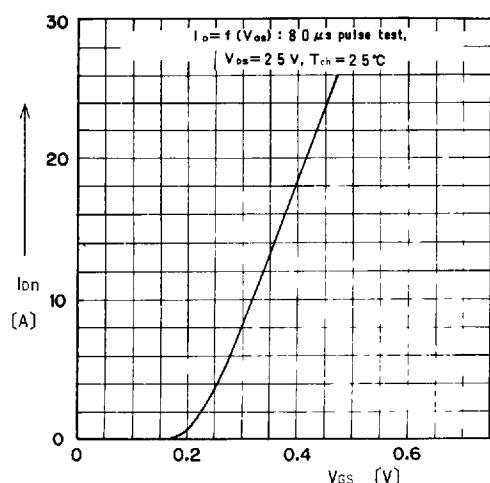
### ■ Equivalent Circuit Schematic



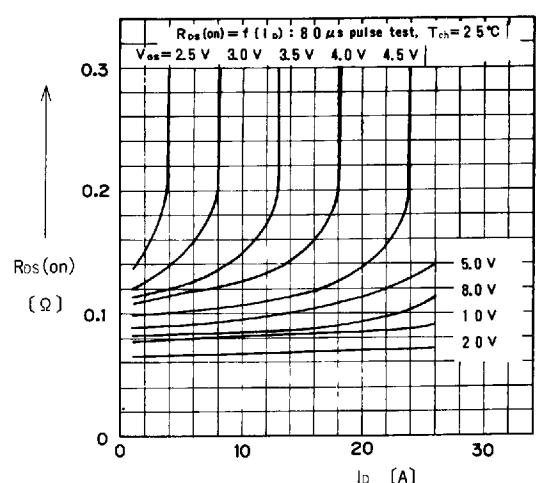
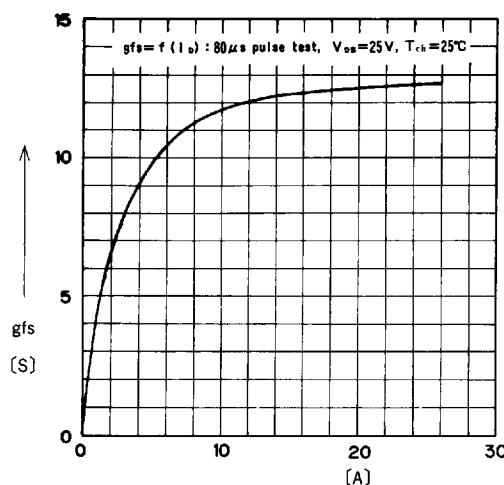
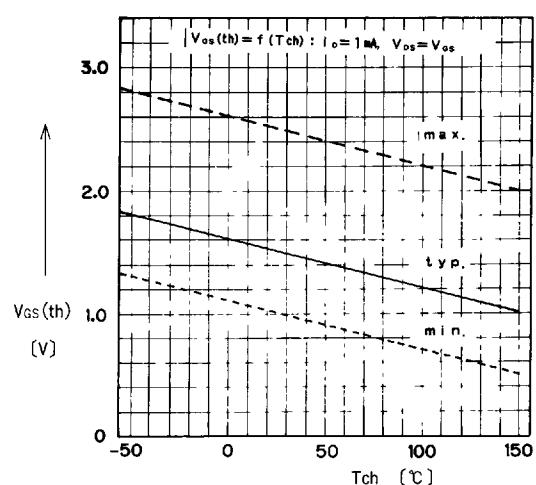
## ■ Characteristics

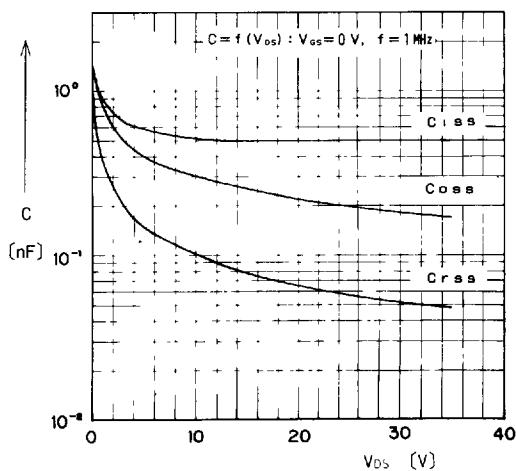
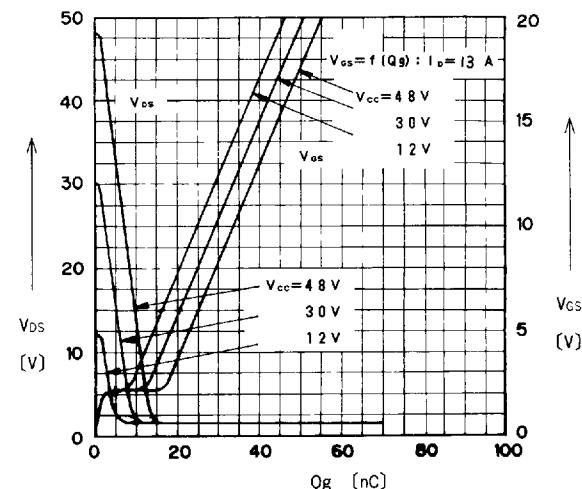


Typical Output Characteristics

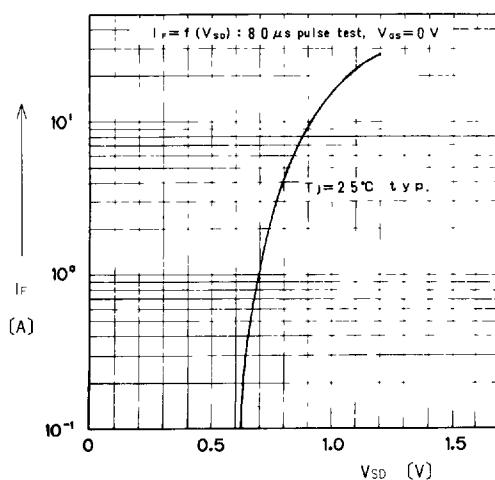
Drain-Source on State Resistance vs.  $T_{ch}$ 

Typical Transfer Characteristic

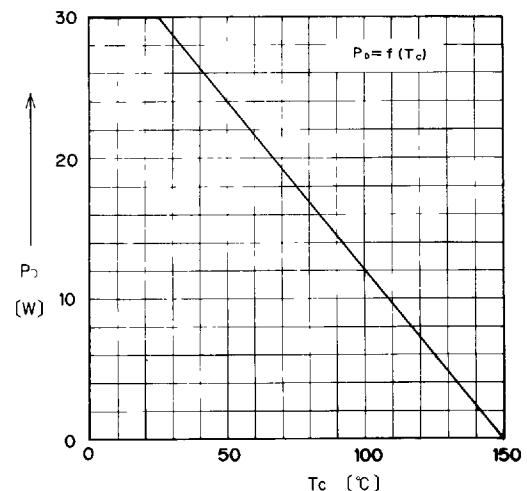
Typical Drain Source on State Resistance vs.  $I_D$ Typical Forward Transconductance vs.  $I_D$ Gate Threshold Voltage vs.  $T_{ch}$

Typical Capacitance vs.  $V_{DS}$ 

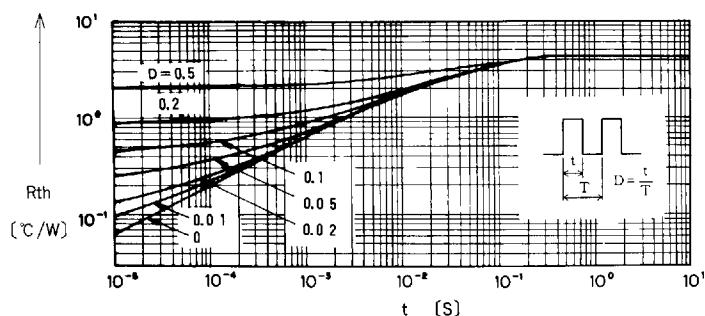
Dynamic Input Characteristics



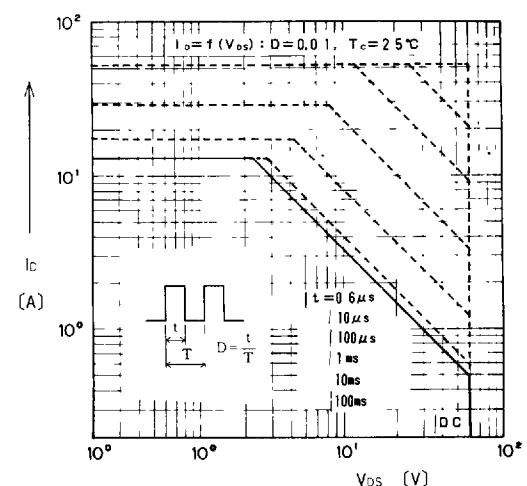
Forward Characteristics of Reverse Diode



Power vs. Temperature Derating



Transient Thermal Impedance



Safe Operating Area